nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

| Based on structural | similarity |
|---------------------|------------|
|---------------------|------------|

| Supplier | | User Part Number | | | | | | |
|---------------------------|------------------------------------|--|-----------------------|-----------|------------|-----------|--|--|
| Nexperia B.V. | | PESD5V0V1BB | | | | | | |
| Name of Laboratory | | Part Description | | | | | | |
| | | Nexperia DHAM | Protection | | | | | |
| Assembly reliability labs | | SMD package | | | | | | |
| Based on AEC-Q101 Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | 241 | | | | | |
| | PC | Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% | 24 hours 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 286 | 21480 | 0 | | |
| # AI | | MIL-STD-750-1 | 5 676165 | 200 | 21400 | 0 | | |
| | HTRB | MIL-STD-750-1 M1038 Method A | | | | | | |
| | | $T_j = T_j max$, $Vr = 100\%$ of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 117 | 9360 | 0 | | |
| | | | | | | | | |
| | тс | JESD22-A104 | | | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 86 | 6880 | 0 | | |
| | | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | 96 hours | 86 | 6880 | 0 | | |
| | | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 86 | 6880 | 0 | | |
| | 701 | MIL-STD-750 Method 1037 | | | | | | |
| | IOL Intermittent Operating Life | ton = toff, devices powered to insure ΔT_j = | 1000 have | | | | | |
| # A5 | Internittent Operating Life | | 1000 hours | n.a. | n.a. | n.a. | | |
| | RSH | JESD22-A111 | | | | | | |
| # C8 | Resistance to Solder Heat | | 10 s | 28 | 840 | 0 | | |
| # 00 | SD | | 10.3 | 20 | 0+0 | 0 | | |
| # C10 | Solderability | J-STD-002 | | 36 | 360 | 0 | | |
| | , | by test chamber set up and does not exceed | | 50 | 500 | 0 | | |

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------|----------|---------|--------------------|------------|
| Nexperia DHAM | Protection | 9360 | 0 | 0.45 | 2.20E+09 |

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